**채용 연계형 인턴 모집 직무 상세 내용**

* **Device Engineer**

**직무내용**

**•** IYM (Integrated Yield Management)

∙ Process integration for mass production (FAB & Sort)

∙ Set KPI goal related to Yield performance (Yield, D0, YLD saving$,...)

∙ FA and problem solving in FAB &Unit probe

∙ Technology/process/product Transfers

• Interface between BE/PL and FAB

∙ Primary contact window for site communication (FAB - Ass`y - BU - QA)

∙ New product and new process introduction to manufacturing (NPD & MRR)

∙ Support B/E open yield/quality issues& projects

∙ Process Change Management (PCP)

**자격요건 및 우대사항**

∙ Need verbal and written communication skills in English

∙ Need understanding of semiconductor fabrication process, basic device physics, statistics, DOE, and analytical skills

∙ Ability to work with open mind and communication actively and share information effectively  
∙ Give priority to experienced applicant on statistical background and semiconductor process

∙ BS in Electronics or Chemical, Material Engineering related subject to Semiconductor process Engineering

* **Process Engineer**

**직무내용**

• Make a powerful & competitive unit process(Productivity / Quality / Cost / Technology).

• Solve a chronic unit process problem.

• Optimize a unstable process.

• Support a development of new devices &Develop new unit process.

• Improve Process Quality of Cp & Cpk.

• Make a cost reduction.

**지원자격 및 우대사항**

• University student who is studying electronics,Semiconductor System Engineering and otherEngineering

• Proficient in Word, Excel, PowerPoint, and Outlook

• Good communication skill in Korean and English

* **Test Engineer**

**직무내용**

• Responsible for sort & final test trouble shooting, program development, yield improvement, PQA Analysis of Discrete product.   
• Develop and release to manufacturing test solutions utilizing Eagle ETS200T,ETS364B, TESEC SP20, and other MOSFET/IGBT ATE platforms.

• Cost saving activity through test time reduction.

• Yield improvement, manufacturing ramp and throughput optimization of new products.

• Sort data analysis by PDF Exensio YMS system.   
• Test development projects such as ultra low resistance (Rdson)

• Measurement static and dynamic (UIL/SW/ Rg) test coverage

• Optimization/improvement, and test efficiency improvement for high performance and multisite testing, high current/voltage testing.  
  
**지원자격 및 우대사항**

• Understanding of basic semiconductor physical properties and electronic circuit.

• Excellent interpersonal skills, able to work well with different levels of people.

• Need oral and written communication skills, including presentation skills in English

• Good software skill and knowledge (Excel,

• Word, PowerPoint, Jump, Minitab, C++, etc.)

* **SiC Tech Development Engineer**

**직무내용**

• Simulation works for verifying the new SiC technology and predicting the device electrical characteristics.

• Analyze SiC technology and trends.

• Creating new SiC device concepts and realizing next generation SiC technologies.  
• SiC derivative technology development from the proven new technology.

• DOE planning to implement the new idea into the experiment and do the evaluation and analysis.

• Cost and yield analysis for the new SiC technologies.

• Cost saving works including yield-up activities for the new SiC technologies.

• Technical support for issues in production

**지원자격 및 우대사항**

• Above BS degree or over in Semiconductor device physics or technology, Microelectronics or equivalent.

• Hand-on experience in power semiconductors design and technology development.  
• Proficiency in TCAD simulation (Synopsys simulator preferred)

• Understanding of material and strong knowledge in device physics, fabrication and characterization principles

• Knowledge and experience in design for reliability and robustness.

• Ability to address design and engineering issues and to provide proper solution.

• Strong communication skills in English.  
• 석사 이상 우대